

Product Bulletin
Document #: PB21873X
Issue Date: 20 September 2017

Title of Change:	Moisture Sensitivity Level (MSL) rating conversion of NCP1611 device family from MSL3 to MSL2.
Effective date:	20 September 2017
Contact information:	Contact your local ON Semiconductor Sales Office or < liri.Konarik@onsemi.com >
Type of notification:	ON Semiconductor will consider this change accepted.
Change category:	☐ Wafer Fab Change ☐ Assembly Change ☐ Test Change ☐ Other - Packaging/Labelling
Change Sub-Category(s): Manufacturing Site Change Manufacturing Process Cha	
Sites Affected: ☐ All site(s) ☐ not ap	oplicable
Description and Purpose:	
The Product Bulletin is to notify customer that the Moisture Sensitivity Level (MSL) rating for NCP1611ADR2G and NCP1611BDR2G products, in our SOIC-8 package, will be updated from MSL3/260 to MSL2/260.	
There is no change in the BOM or packaging, only the label will change to indicate an MSL2 rating.	
Effective 15-September-2017 the label will change from MLS3/260 to MSL2/260.	
The reliability report qualifying this change is available upon request. Please send your request to Sliri.Konarik@onsemi.com to receive a copy.	
List of Affected Standard Parts:	
NCP1611ADR2G NCP1611BDR2G	

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